

MA2J1120G

Silicon epitaxial planar type

For switching circuits

■ Features

- Allowing high-density mounting
- Ensuring the forward current (Average) capacity $I_{F(AV)} = 200 \text{ mA}$

■ Package

- Code
SMini2-F3
- Pin Name
1: Anode
2: Cathode

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V_{RM}	40	V
Forward current (Average) *1	$I_{F(AV)}$	200	mA
Peak forward current	I_{FM}	600	mA
Non-repetitive peak forward surge current *2	I_{FSM}	1	A
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Marking Symbol: 1C

Note) *1: With a printed-circuit board

*2: $t = 1 \text{ s}$

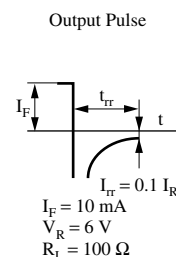
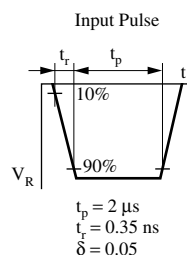
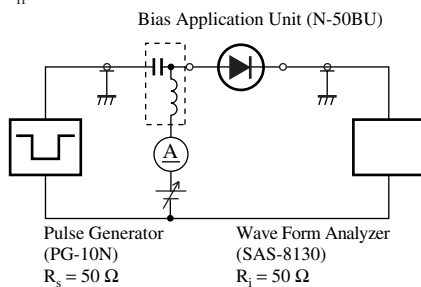
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

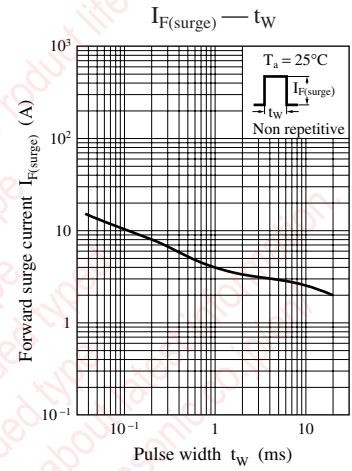
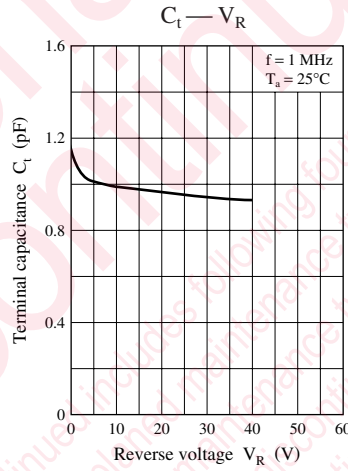
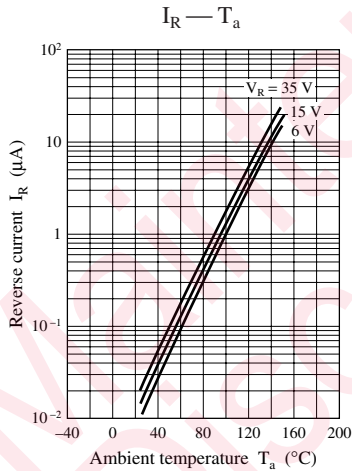
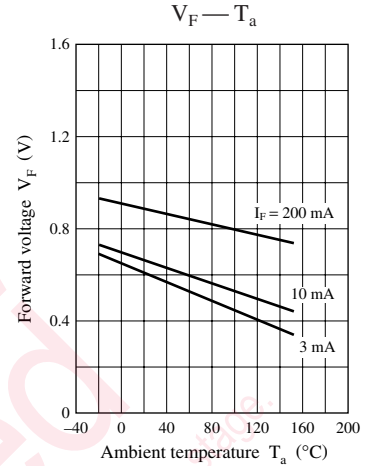
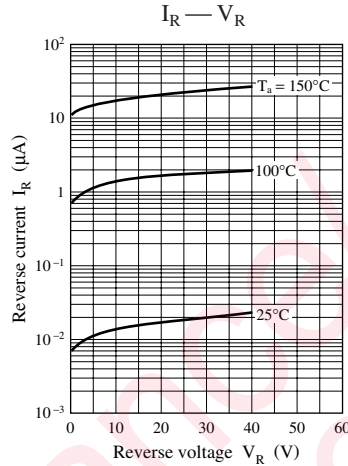
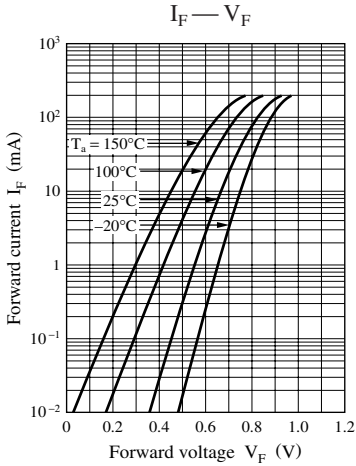
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200 \text{ mA}$			1.1	V
Reverse current	I_{R1}	$V_R = 15 \text{ V}$			50	nA
	I_{R2}	$V_R = 35 \text{ V}$			500	nA
	I_{R3}	$V_R = 35 \text{ V}, T_a = 100^\circ\text{C}$			100	μA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			4	pF
Reverse recovery time *	t_{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$ $I_{tr} = 0.1 I_R, R_L = 100 \Omega$			10	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

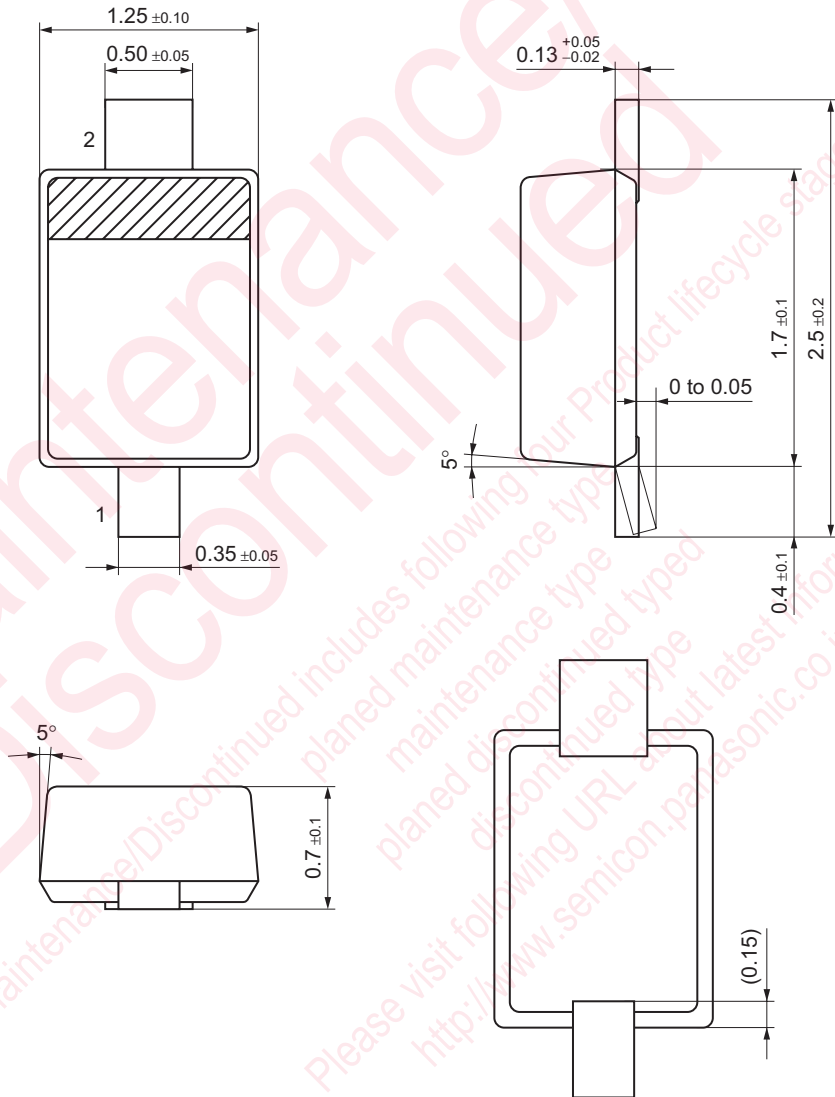
3. *: t_{rr} measurement circuit





SMini2-F3

Unit: mm



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